

<b>PCN Number:</b>	20200127000.1	<b>PCN Date:</b>	Feb. 18, 2020
<b>Title:</b>	Qualification of new Mold & Mount Compound for Select Devices		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	May 18, 2020	<b>Estimated Sample Availability:</b>	Date provided at sample request
<b>Change Type:</b>			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process
<b>PCN Details</b>			
<b>Description of Change:</b>			
Texas Instruments is pleased to announce the qualification of a new mount and mold compound for the devices in the Product Affected section below as follows:			
<b>Group 1 device:</b>			
	<b>Current</b>	<b>New</b>	
Mount Compound	1400013111	1400160111	
Mold Compound	18003331G1	180082310F	
<b>Group 2 device:</b>			
	<b>Current</b>	<b>New</b>	
Mount Compound	1400013111	1400153112	
Mold Compound	1800008131	18008231U1	
<b>Reason for Change:</b>			
Continuity of supply. Current mount compound and mold compound material is no longer available.			
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>			
None			
<b>Anticipated impact on Material Declaration</b>			
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI ECO website</a> .
<b>Changes to product identification resulting from this PCN:</b>			
None			
<b>Product Affected: Group 1</b>			
LM97593VH/NOPB			
<b>Product Affected: Group 2</b>			
DP83848VYB/NOPB	DP83848YB/NOPB	DP83848YBX/NOPB	

# Qualification Report

Approve Date 16-Jan-2020

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: DP83848YB/NOPB	Qual Device: LM97593VH/NOPB
PC	Preconditioning	Level 3 - 245C	-	3/924/0
PC	Preconditioning	Level 3 - 260C	3/693/0	-
AC	Autoclave, 121C	96 Hours	3/231/0	3/231/0
BHAST	Biased HAST, 110C	264 Hours	-	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0	3/231/0
TC	Temperature Cycle, - 65C/150C	500 Cycles	3/224/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	3/90/0	3/90/0
SD	Solderability, Pb	Steam age, 8 Hours	3/66/0	3/66/0
SD	Solderability, Pb-Free	Steam age, 8 Hours	3/66/0	3/66/0
MQ	Manufacturability	Per mfg. site specification	3/Pass	3/Pass
DS	Die Shear	Die	3/30/0	3/30/0
PD	Physical Dimensions	Per mechanical drawing	3/15/0	3/15/0
LFA	Lead Finish Adhesion	Leads, min. 3 units	3/45/0	3/45/0
YLD	FTY and Bin Summary	-	3/Pass	3/Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1000 Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1000 Hours, and 170C/420 Hours

- The following are equivalent Temperature Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

### Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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